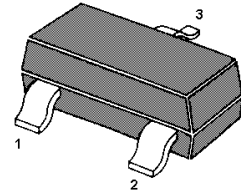
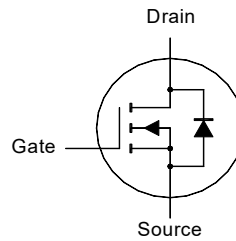


MMFTN2302B

N-Channel Enhancement Mode MOSFET

Applications

- Load Switching for Portable Devices
- DC-DC converter



1. Gate 2. Source 3. Drain
SOT-23 Plastic Package

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$ unless otherwise specified)

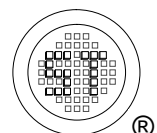
Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V_{DS}	20	V	
Gate-Source Voltage	V_{GS}	± 8	V	
Continuous Drain Current	I_D	2.9	A	
Peak Drain Current, Pulsed ¹⁾	I_{DM}	10	A	
Power Dissipation ²⁾	Steady State $t \leq 10$ s	P_D	0.71	W
			1.4	
Operating Junction and Storage Temperature Range	T_j, T_{stg}	- 55 to + 150	$^\circ\text{C}$	

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	Steady State	176
		$t \leq 10$ s	89

¹⁾ Pulse Test: Pulse Width $\leq 100 \mu\text{s}$, Duty Cycle $\leq 2\%$, Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.

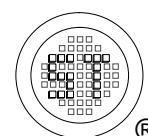
²⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



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Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	$V_{(BR)DSS}$	20	-	-	V
Drain-Source Leakage Current at $V_{DS} = 20 \text{ V}$	I_{DSS}	-	-	1	μA
Gate-Source Leakage Current at $V_{GS} = \pm 8 \text{ V}$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	$V_{GS(th)}$	0.4	-	0.85	V
Drain-Source On-State Resistance at $V_{GS} = 4.5 \text{ V}, I_D = 3.6 \text{ A}$ at $V_{GS} = 2.5 \text{ V}, I_D = 3.1 \text{ A}$	$R_{DS(on)}$	- -	- -	57 75	m Ω
DYNAMIC PARAMETERS					
Forward Transconductance at $V_{DS} = 5 \text{ V}, I_D = 3.6 \text{ A}$	g_{FS}	-	9	-	S
Gate Resistance at $V_{DS} = 0 \text{ V}, f = 1 \text{ MHz}$	R_g	-	0.6	-	Ω
Input Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	-	610	-	pF
Output Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	-	95	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	-	72	-	pF
Gate Charge Total at $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.6 \text{ A}$	Q_g	-	8.7	-	nC
Gate to Source Gate Charge at $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.6 \text{ A}$	Q_{gs}	-	1.6	-	nC
Gate to Drain Charge at $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.6 \text{ A}$	Q_{gd}	-	3.3	-	nC
Turn-On Delay Time at $V_{DD} = 10 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 4.5 \text{ V}, R_G = 2.2 \Omega$	$t_{d(on)}$	-	12	-	ns
Rise Time at $V_{DD} = 10 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 4.5 \text{ V}, R_G = 2.2 \Omega$	t_r	-	30	-	ns
Turn-Off Delay Time at $V_{DD} = 10 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 4.5 \text{ V}, R_G = 2.2 \Omega$	$t_{d(off)}$	-	13	-	ns
Fall Time at $V_{DD} = 10 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 4.5 \text{ V}, R_G = 2.2 \Omega$	t_f	-	2.3	-	ns
Body-Diode PARAMETERS					
Body Diode Voltage at $I_S = 0.95 \text{ A}$	V_{SD}	-	-	1.2	V
Body Diode Reverse Recovery Time at $I_S = 3.6 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	t_{rr}	-	12	-	ns
Body Diode Reverse Recovery Charge at $I_S = 3.6 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	Q_{rr}	-	2.2	-	nc



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Electrical Characteristics Curves

Fig. 1 Typical Output Characteristic

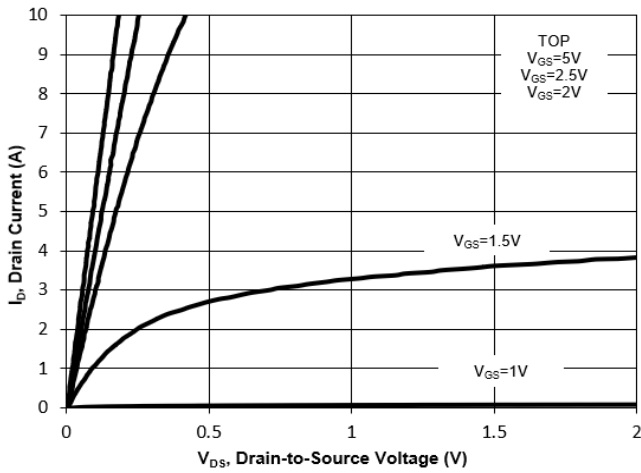


Fig. 2 Typical Transfer Characteristic

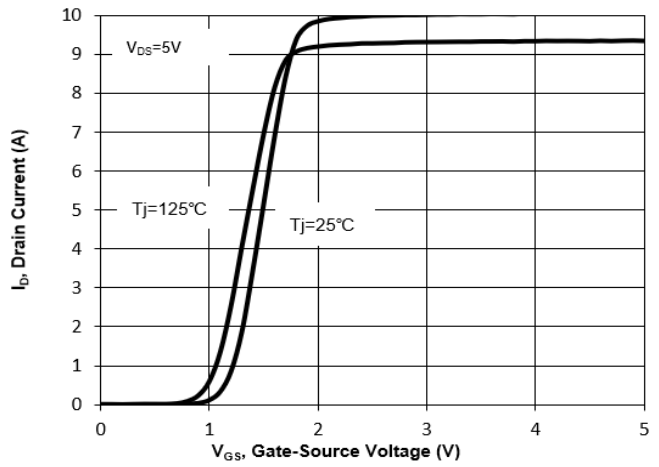


Fig. 3 on-Resistance vs Drain Current

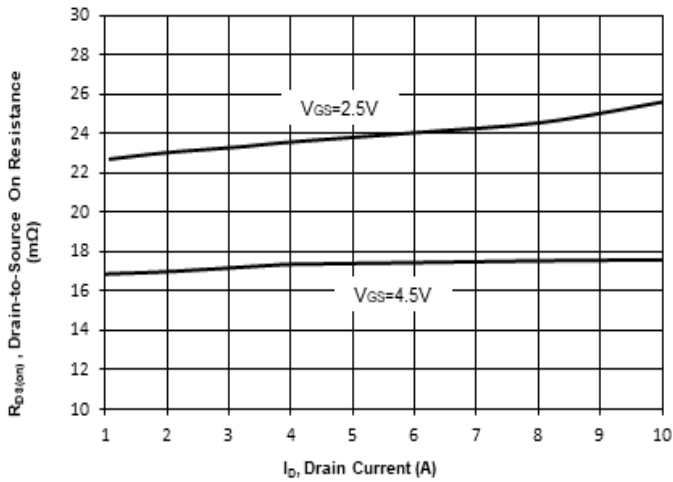


Fig. 4 on-Resistance vs. Gate Voltage

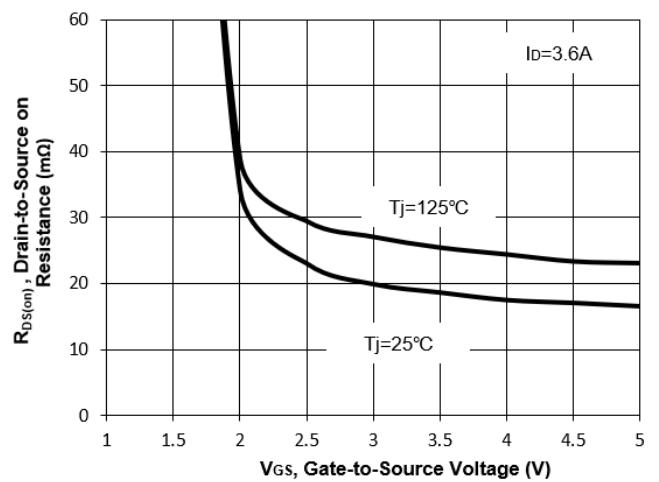


Fig. 5 on-Resistance vs. T_J

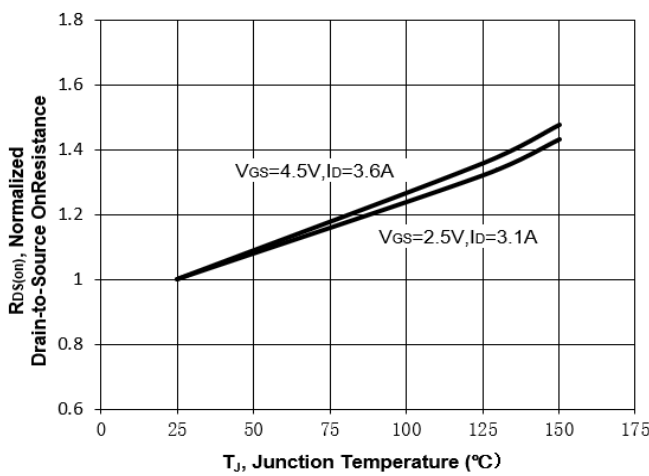
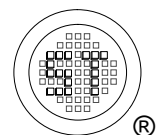
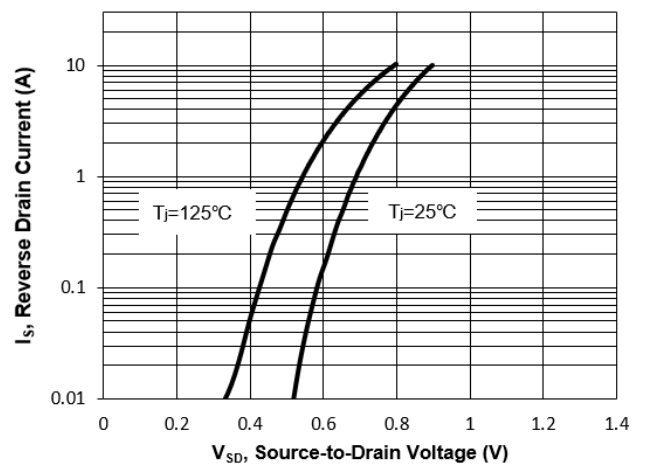


Fig. 6 Typical Forward Characteristic



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Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

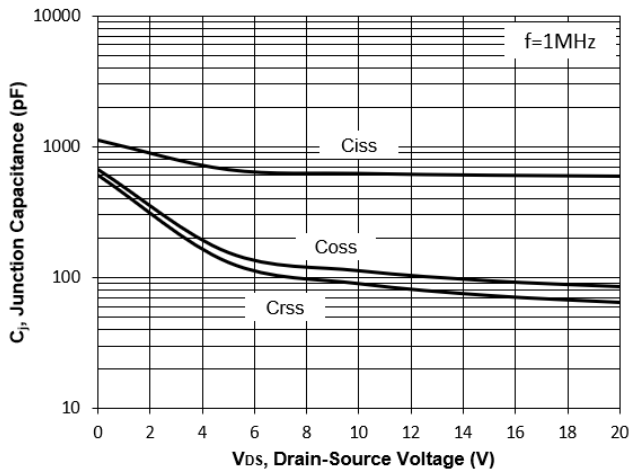


Fig. 8 Drain-Source Leakage Current vs. T_j

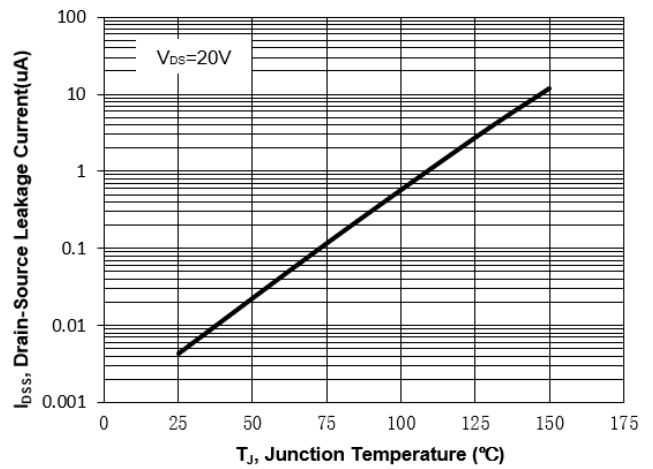


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

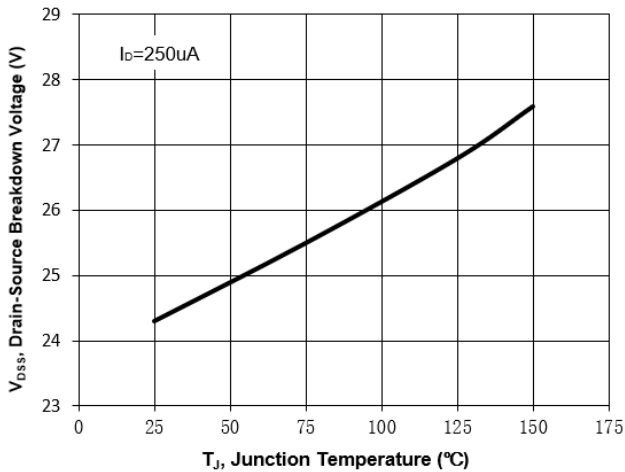


Fig. 10 Gate Threshold Variation vs. T_j

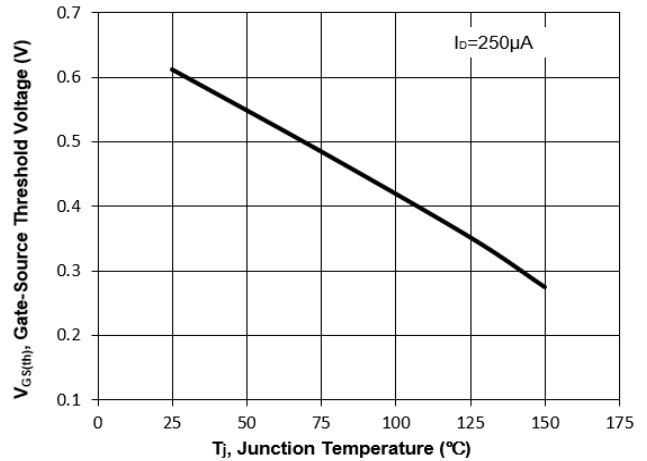


Fig. 11 Gate Charge

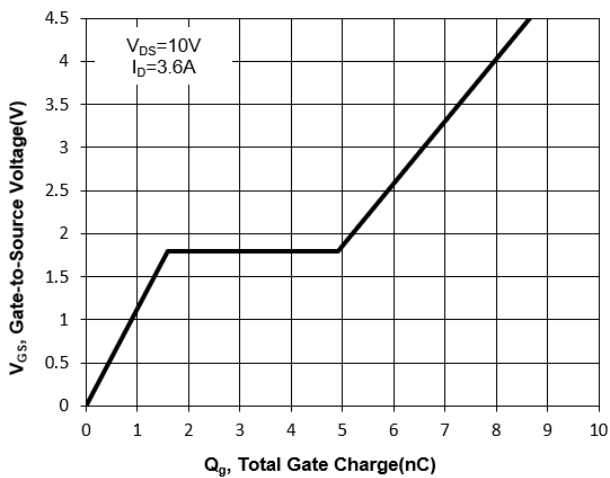
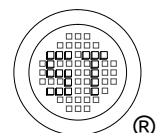
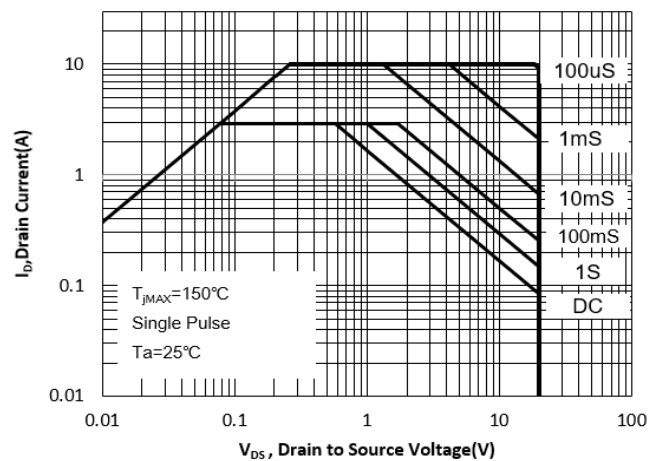


Fig. 12 Safe Operation Area



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Test Circuits

Fig.1-1 Switching times test circuit

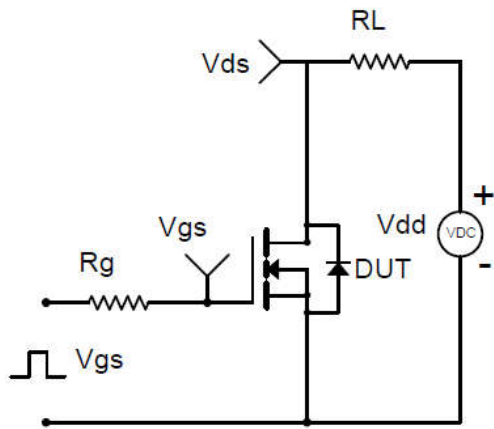


Fig.1-2 Switching Waveform

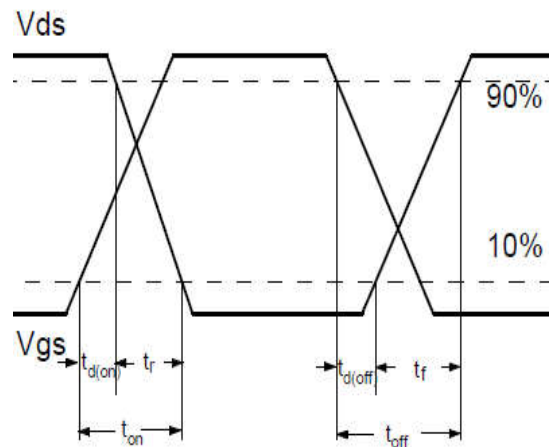


Fig.2-1 Gate charge test circuit

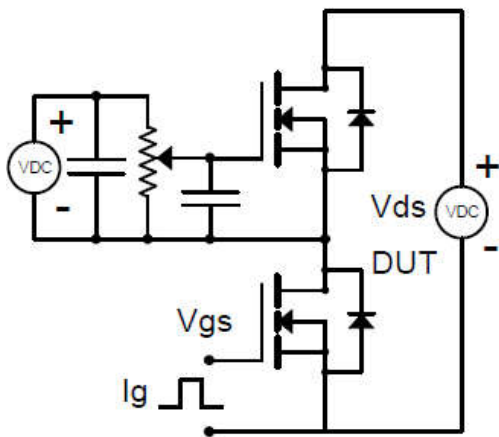
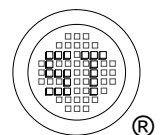
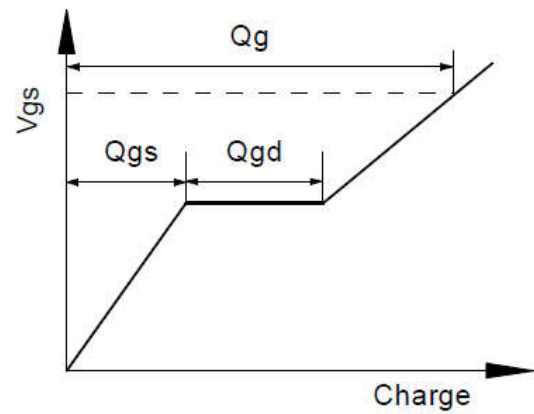


Fig.2-2 Gate charge waveform

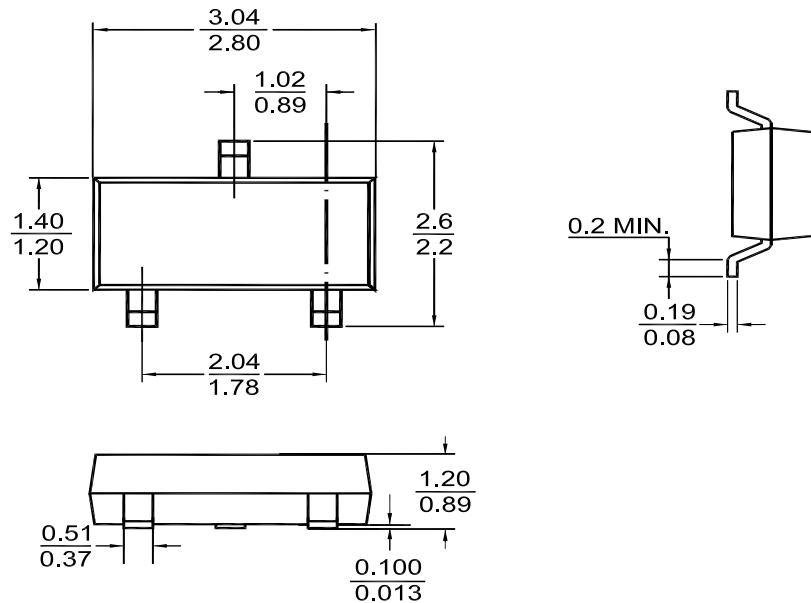


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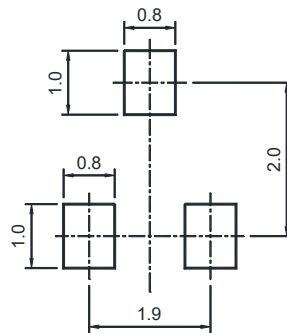
PACKAGE OUTLINE

Plastic surface mounted package (Dimensions in mm)

SOT-23



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" TP " = Part No.
 "YM" = Date Code Marking
 "Y" = Year
 "M" = Month
 Font type: Arial

